



30V N-Channel MOSFETs

General Description

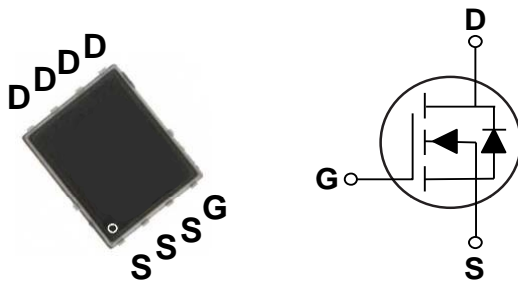
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
30 V	5.5 mΩ	80 A

Features

- R_{DS(ON)} ≤ 5.5mΩ@V_{GS}=10V
- Fast switching
- Improved dv/dt capability
- Green Device Available

PPAK5X6 Pin Configuration



Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current - Continuous (T _C =25°C)	80	A
	Drain Current - Continuous (T _C =100°C)	51	A
I _{DM}	Drain Current - Pulsed (NOTE 1)	320	A
EAS	Single Pulse Avalanche Energy (NOTE 2)	88	mJ
IAS	Single Pulse Avalanche Current (NOTE 2)	42	A
P _D	Power Dissipation (T _C =25°C)	74	W
	Power Dissipation - Derate above 25°C	0.59	W/°C
T _J	Operating Junction Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
Marking Code		NC5P5A	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to Ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	1.7	°C/W

**Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)****Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$R_{DS(ON)}$	Static Drain-Source On-Resistance (NOTE 3)	$V_{GS}=10V, I_D=20A$	---	4.6	5.5	m Ω
		$V_{GS}=4.5V, I_D=10A$	---	6.5	8.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.6	2.5	V
gfs	Forward Transconductance	$V_{DS}=10V, I_D=10A$	---	18	---	S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge	$V_{DS}=15V, V_{GS}=4.5V, I_D=20A$ (NOTE 3 & 4)	---	11.1	---	nC
Q_{gs}	Gate-Source Charge		---	1.85	---	
Q_{gd}	Gate-Drain Charge		---	6.8	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=15A$ (NOTE 3 & 4)	---	7.5	---	nS
T_r	Rise Time		---	14.5	---	
$T_{d(off)}$	Turn-Off Delay Time		---	35.2	---	
T_f	Fall Time		---	9.6	---	
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$	---	1160	---	pF
C_{oss}	Output Capacitance		---	200	---	
C_{rss}	Reverse Transfer Capacitance		---	180	---	
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$	---	2.5	---	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{DD}=25V, L=0.1\text{mH}, I_{AS}=20A$	20	---	---	mJ

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	80	A
I_{SM}	Pulsed Source Current (NOTE 3)		---	---	320	A
V_{SD}	Diode Forward Voltage (NOTE 3)	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1	V

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=42A, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.



Characteristics Curves

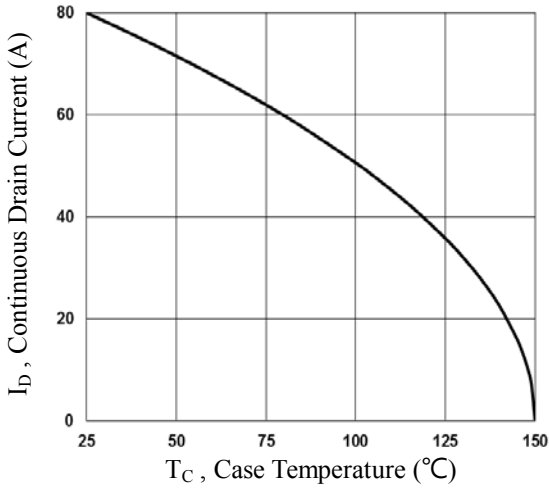


Fig.1 Continuous Drain Current vs. T_C

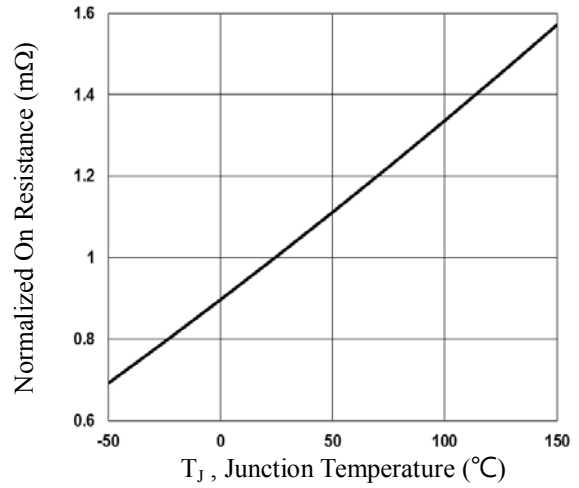


Fig.2 Normalized RDSON vs. T_J

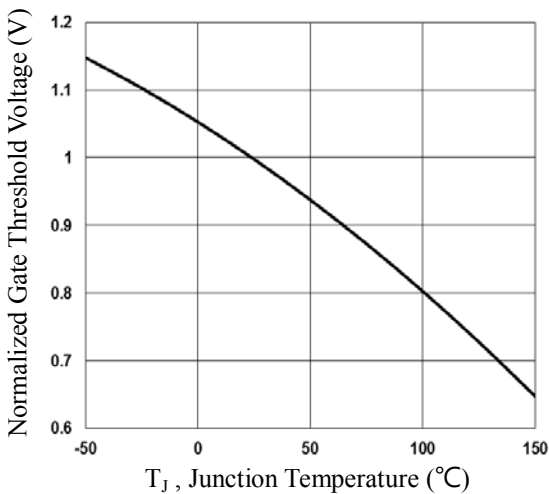


Fig.3 Normalized V_{th} vs. T_J

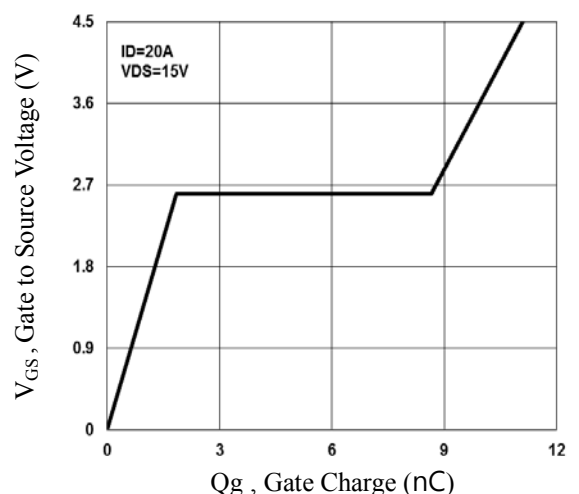


Fig.4 Gate Charge Waveform

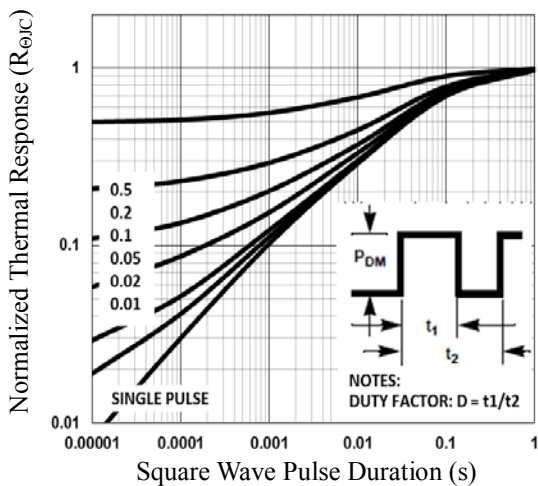


Fig.5 Normalized Transient Impedance

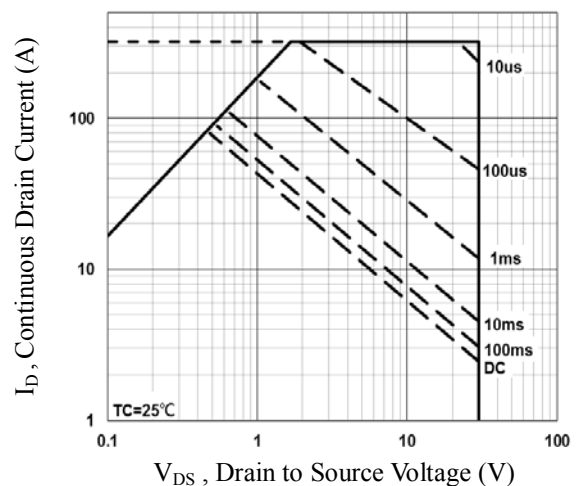


Fig.6 Maximum Safe Operation Area



Characteristics Curves

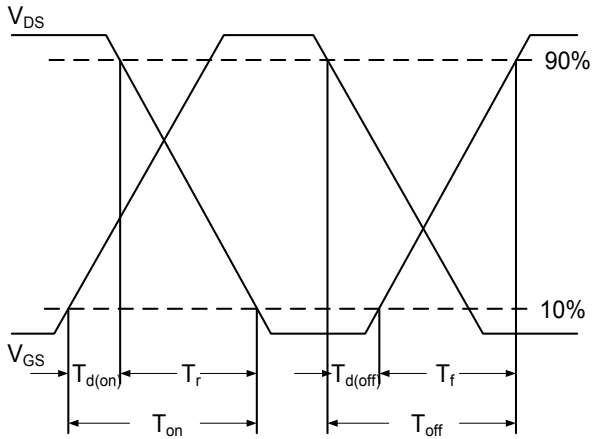
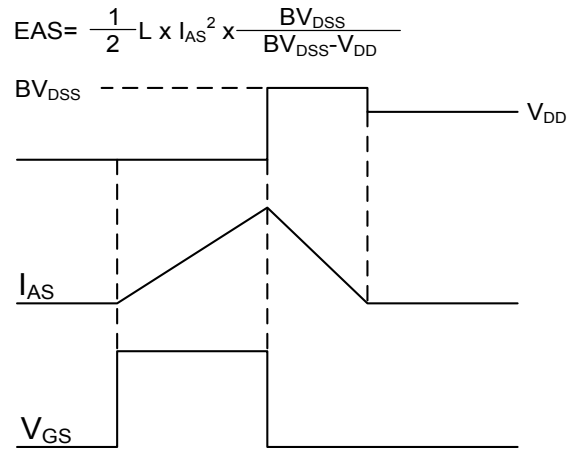


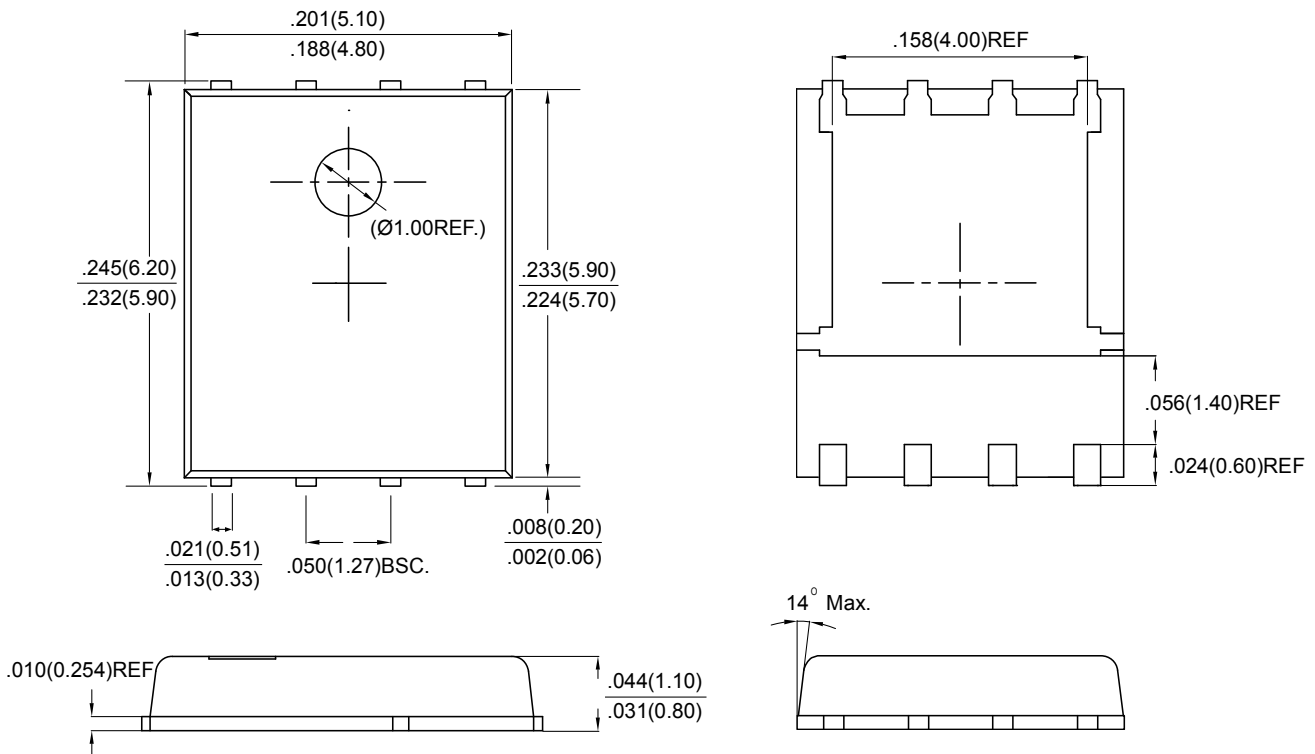
Fig.7 Switching Time Waveform



$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

Fig.8 EAS Waveform

Package Outline Dimensions



PPAK5X6

Dimensions in inches and (millimeters)



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